



Material Content Data Sheet



Sales Product Name		BSS123N H6327		Issued		24. January 2018		
MA#		MA001627154						
Package		PG-SOT23-3-5		Weight*		9.32 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.006	0.06		633	
	non noble metal	tin	7440-31-5	0.002	0.02		163	
	inorganic material	silicon	7440-21-3	0.090	0.97	1.05	9658	10454
leadframe	non noble metal	chromium	7440-47-3	0.009	0.10		970	
	inorganic material	silicon	7440-21-3	0.001	0.01		65	
	non noble metal	titanium	7440-32-6	0.003	0.03		323	
wire	non noble metal	copper	7440-50-8	3.000	32.18	32.32	321846	323204
	non noble metal	copper	7440-50-8	0.008	0.09	0.09	893	893
	encapsulation	organic material	carbon black	1333-86-4	0.058	0.62		6189
encapsulation	plastics	epoxy resin	-	1.240	13.31		133061	
	inorganic material	silicondioxide	60676-86-0	4.471	47.95	61.88	479638	618888
leadfinish	non noble metal	tin	7440-31-5	0.150	1.61	1.61	16052	16052
plating	noble metal	silver	7440-22-4	0.284	3.05	3.05	30509	30509
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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